

PRELIMINARY AMENDMENT
U.S. Appln. No.: based on PCT/JP00/05044

Q68281

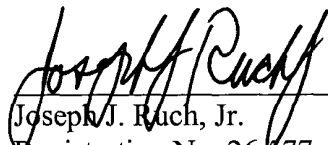
REMARKS

Claims 4, 5, 10, 17, 18, 21, 26, 27, 28, and 35 have been amended to place the claims in desired appropriate form for examination. Thus all of the claims are now in appropriate form, and the Examiner is respectfully requested to proceed with the examination.

Early favorable action is earnestly solicited.

In the event that the Examiner believes that it may facilitate the further prosecution of this application, the Examiner is invited to contact the undersigned attorney at the local Washington, D.C. telephone number indicated below.

Respectfully submitted,



Joseph J. Ruch, Jr.
Registration No. 26,577

SUGHRUE MION, PLLC
2100 Pennsylvania Avenue, N.W.
Washington, D.C. 20037-3213
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

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APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION:

The specification is changed as follows:

Amend the specification by inserting before the first line the sentence:

This is a National stage entry under 35 U.S.C. § 371 of PCT Application No. PCT/JP00/05044 filed July 28, 2000; the above noted application is hereby incorporated by reference.

IN THE CLAIMS:

The claims are amended as follows:

4. (amended) The multilayered printed circuit board according to ~~any of claims 1 to 3~~ claim 1,

wherein said solder resist layer contains an elastomer.

5. A solder resist composition to be used for manufacturing the multilayered printed circuit board according to ~~any of claims 1 to 4~~ claim 1,

wherein an inorganic filler is mixed with a paste containing a resin for a solder resist layer.

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10. (amended) The multilayered printed circuit board according to ~~any of claims 7 to 9~~
claim 7,

wherein said solder resist layer contains an inorganic filler.

17. (amended) The multilayered printed circuit board according to ~~any of claims 14, 15 or~~
~~16~~ claim 14,

wherein said solder resist layer has a dielectric loss tangent of 0.01 or lower at 1 GHz.

18. (amended) The multilayered printed circuit board according to ~~any of claims 14 to 17~~
claim 14,

wherein said solder resist layer is comprising a cycloolefin type resin.

21. (amended) The multilayered printed circuit board according to ~~any of claims 14 to 20~~
claims 14,

wherein said resin insulating layer is comprising a polyolefin type resin or a
polyphenylene type resin.

26. (amended) The multilayered printed circuit board according to ~~any of claims 23, 24 or~~
~~25~~ claim 23,

wherein said solder resist layer has a dielectric constant of 3.0 or lower at 1 GHz.

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27. (amended) The multilayered printed circuit board according to ~~any of claims 24, 25~~
~~or 26~~ claim 24,

wherein said polyphenylene ether resin is a thermosetting type polyphenylene ether
resin and/or thermoplastic type polyphenylene ether resin.

28. (amended) The multilayered printed circuit board according to ~~any of claims 23 to 27~~
claim 23,

wherein said resin insulating layer is comprising a polyphenylene ether resin.

35. (amended) The multilayered printed circuit board according to ~~any of claims 30 to 34~~
claims 30,

wherein said solder resist layer contains at least one member selected from the group
consisting of a silicon compound, an aluminum compound and a magnesium compound.